ICS 31.080 SLOVENSKÁ TECHNICKÁ NORMA September 2014

STN	**Normalizácia rozmerov polovodičových súčiastok. Časť 4: Systém kódovania a triedenia podľa tvaru puzdier polovodičových súčiastok.**	**STN EN 60191-4** 35 8791

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 08/14

Obsahuje: EN 60191-4:2014, IEC 60191-4:2013

Oznámením tejto normy sa od 14.11.2016 ruší
STN EN 60191-4 (35 8791) z augusta 2001

119317

EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN 60191-4

March 2014

ICS 31.080

Supersedes EN 60191-4:1999 + A1:2002 + A2:2002

English version

Mechanical standardization of semiconductor devices - Part 4: Coding system and classification into forms of package outlines for semiconductor device packages

(IEC 60191-4:2013)

Normalisation mécanique des dispositifs à semiconducteurs -
Partie 4: Système de codification et classification en formes des boîtiers pour dispositifs à semiconducteurs
(CEI 60191-4:2013)

Mechanische Normung von Halbleiterbauelementen -
Teil 4: Codierungssystem für Gehäuse und Eingruppierung der Gehäuse nach der Gehäuseform für Halbleiterbauelemente
(IEC 60191-4:2013)

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B - 1000 Brussels

Foreword

The text of document 47D/837/FDIS, future edition 3 of IEC 60191-4, prepared by SC 47D, Semiconductor devices packaging, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60191-4:2014.

The following dates were fixed:

– latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2014-09-21
– latest date by which the national standards conflicting with the EN have to be withdrawn	(dow)	2016-11-14

This European Standard supersedes EN 60191-4:1999 and its Amendments A1:2002 and A2:2002.

EN 60191-4:2014 includes the following significant changes with respect to EN 60191-4:1999:

a) Material code "S" is added to indicate a silicon based package.

b) Description of "WL" is added to be used for general use.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN and CENELEC shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC 60191-4:2013 was approved by CENELEC as a European Standard without any modification.

IEC 60191-4

Edition 3.0 2013-10

INTERNATIONAL STANDARD

NORME INTERNATIONALE

colour inside

Mechanical standardization of semiconductor devices – Part 4: Coding system and classification into forms of package outlines for semiconductor device packages

Normalisation mécanique des dispositifs à semiconducteurs – Partie 4: Système de codification et classification en formes des structures des boîtiers pour dispositifs à semiconducteurs

IEC 60191-4:2013

About the IEC

The International Electrotechnical Commission (IEC) is the leading global organization that prepares and publishes International Standards for all electrical, electronic and related technologies.

About IEC publications

The technical content of IEC publications is kept under constant review by the IEC. Please make sure that you have the latest edition, a corrigenda or an amendment might have been published.

Useful links:

IEC publications search - www.iec.ch/searchpub

The advanced search enables you to find IEC publications by a variety of criteria (reference number, text, technical committee,…).
It also gives information on projects, replaced and withdrawn publications.

IEC Just Published - webstore.iec.ch/justpublished

Stay up to date on all new IEC publications. Just Published details all new publications released. Available on-line and also once a month by email.

Electropedia - www.electropedia.org

The world's leading online dictionary of electronic and electrical terms containing more than 30 000 terms and definitions in English and French, with equivalent terms in additional languages. Also known as the International Electrotechnical Vocabulary (IEV) on-line.

Customer Service Centre - webstore.iec.ch/csc

If you wish to give us your feedback on this publication or need further assistance, please contact the Customer Service Centre: csc@iec.ch.

A propos de la CEI

La Commission Electrotechnique Internationale (CEI) est la première organisation mondiale qui élabore et publie des Normes internationales pour tout ce qui a trait à l'électricité, à l'électronique et aux technologies apparentées.

A propos des publications CEI

Le contenu technique des publications de la CEI est constamment revu. Veuillez vous assurer que vous possédez l'édition la plus récente, un corrigendum ou amendement peut avoir été publié.

Liens utiles:

Recherche de publications CEI - www.iec.ch/searchpub

La recherche avancée vous permet de trouver des publications CEI en utilisant différents critères (numéro de référence, texte, comité d'études,…).
Elle donne aussi des informations sur les projets et les publications remplacées ou retirées.

Just Published CEI - webstore.iec.ch/justpublished

Restez informé sur les nouvelles publications de la CEI. Just Published détaille les nouvelles publications parues. Disponible en ligne et aussi une fois par mois par email.

Electropedia - www.electropedia.org

Le premier dictionnaire en ligne au monde de termes électroniques et électriques. Il contient plus de 30 000 termes et définitions en anglais et en français, ainsi que les termes équivalents dans les langues additionnelles. Egalement appelé Vocabulaire Electrotechnique International (VEI) en ligne.

Service Clients - webstore.iec.ch/csc

Si vous désirez nous donner des commentaires sur cette publication ou si vous avez des questions contactez-nous: csc@iec.ch.

IEC 60191-4

Edition 3.0 2013-10

INTERNATIONAL STANDARD

NORME INTERNATIONALE

colour inside

Mechanical standardization of semiconductor devices – Part 4: Coding system and classification into forms of package outlines for semiconductor device packages

Normalisation mécanique des dispositifs à semiconducteurs – Partie 4: Système de codification et classification en formes des structures des boîtiers pour dispositifs à semiconducteurs

INTERNATIONAL ELECTROTECHNICAL COMMISSION

COMMISSION ELECTROTECHNIQUE INTERNATIONALE

PRICE CODE
CODE PRIX T

ICS 31.080

ISBN 978-2-8322-1155-7

CONTENTS

INTERNATIONAL ELECTROTECHNICAL COMMISSION

_____

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 4: Coding system and classification into forms of package outlines for semiconductor device packages

FOREWORD

1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as “IEC Publication(s)”). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
6) All users should ensure that they have the latest edition of this publication.
7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 60191-4 has been prepared by subcommittee 47D: Semiconductor devices packaging, of IEC technical committee 47: Semiconductor devices.

This third edition cancels and replaces the second edition published in 1999, Amendment 1:2001 and Amendment 2:2002.This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) Material code "S" is added to indicate a silicon based package.
b) Description of "WL" is added to be used for general use.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/837/FDIS	47D/848/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all the parts in the IEC 60191 series, published under the general title *Mechanical standardization of semiconductor devices*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 4: Coding system and classification into forms of package outlines for semiconductor device packages

1 Scope

This part of IEC 60191 specifies a method for the designation of package outlines and for the classification of forms of package outlines for semiconductor devices and a systematic method for generating universal descriptive designators for semiconductor device packages.

The descriptive designator provides a useful communication tool but has no implied control for assuring package interchangeability.